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Application No. Not Yet Assigned Paper Dated January 6, 2006 In Reply to USPTO Correspondence of N/A Attorney Docket No. 1217-053827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.

Not Yet Assigned

Applicant

Naoya SAIKI

Filed

Concurrently Herewith

Title

HARDENABLE PRESSURE SENSITIVE

ADHESIVE SHEET FOR DICING/DIE-BONDING

AND METHOD FOR MANUFACTURING

SEMICONDUCTOR DEVICE

International Application No.:

PCT/JP2004/009629

International Filing Date

07 July 2004

Priority Date(s) Claimed

08 July 2003

MAIL STOP PCT Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Sir:

Prior to initial examination, please amend the above-identified patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Amendments to the Abstract begin on page 9 of this paper.

Remarks begin on page 10 of this paper.